

**1. Scope :**

This specification applies to silicon zener double diodes Flip chips, Device NO. SD-71213GF-A

**2. Structure :**

- 2-1. Planar type : PNP, Zener Double Diodes.
- 2-2. Electrodes :  
Top side : SnAu Alloy.

**3. Size :**

- 3-1. \*Chip size : 17.5 mils x 9.3 mils (0.445 mm x 0.235 mm).
- 3-2. Chip thickness :  $2.8 \pm 0.6$  mils ( $0.070 \pm 0.015$  mm).
- 3-3. Top SnAu bonding pads : 4.2 mils x 5.5 mils x 2 (0.107 mm x 0.140 mm x 2).
- 3-4. The distance between dual bonding pad: 5.5 mils (0.140 mm).
- 3-5. Pattern drawing : Refer to the attached drawing.

\*Including scribing line. The chip size is about  $(0.420 \pm 0.015) \times (0.210 \pm 0.015)$  mm<sup>2</sup> after dicing.

**4. Electrical characteristics (Ta = 25 °C)**

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse Leakage Current	$I_R$	$V_R=9V$ $E_e=0mW/cm^2$			100	nA
Zener Voltage	$V_Z$	$I_Z=5mA$ $E_e=0mW/cm^2$	11		15	V

